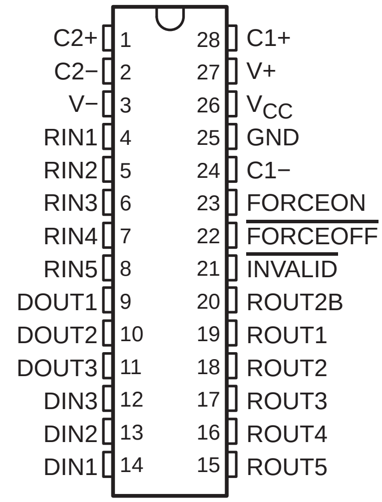
- **Operate With 3-V to 5.5-V V_{CC} Supply**
- **Always-Active Noninverting Receiver Output (ROUT2B)**
- **Low Standby Current . . . 1 μA Typical**
- **External Capacitors . . . 4 × 0.1 μF**
- **Accept 5-V Logic Input With 3.3-V Supply**
- **Inter-Operable With SN65C3238, SN75C3238**
- **Support Operation From 250 kbit/s to 1 Mbit/s**
- **RS-232 Bus-Pin ESD Protection Exceeds ±15-kV Using Human-Body Model (HBM)**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **Applications**
  - **Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment**

DB, DW, OR PW PACKAGE
(TOP VIEW)



description/ordering information

The SN65C3243 and SN75C3243 consist of three line drivers, five line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin-to-pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, these devices include an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the devices are powered down. The devices operate at data signaling rates up to 1 Mbit/s and an increased slew-rate range of 24 V/μs to 150 V/μs.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−0°C to 70°C	SOIC (DW)	Tube of 20	SN75C3243DW	75C3243
		Reel of 1000	SN75C3243DWR	
	SSOP (DB)	Reel of 2000	SN75C3243DBR	75C3243
	TSSOP (PW)	Tube of 50	SN75C3243PW	CA3243
		Reel of 2000	SN75C3243PWR	
−40°C to 85°C	SOIC (DW)	Tube of 20	SN65C3243DW	65C3243
		Reel of 1000	SN65C3243DWR	
	SSOP (DB)	Reel of 2000	SN65C3243DBR	65C3243
	TSSOP (PW)	Tube of 50	SN65C3243PW	65C3243
		Reel of 2000	SN65C3243PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the devices do not sense a valid RS-232 signal, the driver outputs are disabled. If $\overline{\text{FORCEOFF}}$ is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 µA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The $\overline{\text{INVALID}}$ output is used to notify the user if an RS-232 signal is present at any receiver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than −2.7 V or has been between −0.3 V and 0.3 V for less than 30 µs. $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltages are between −0.3 V and 0.3 V for more than 30 µs. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

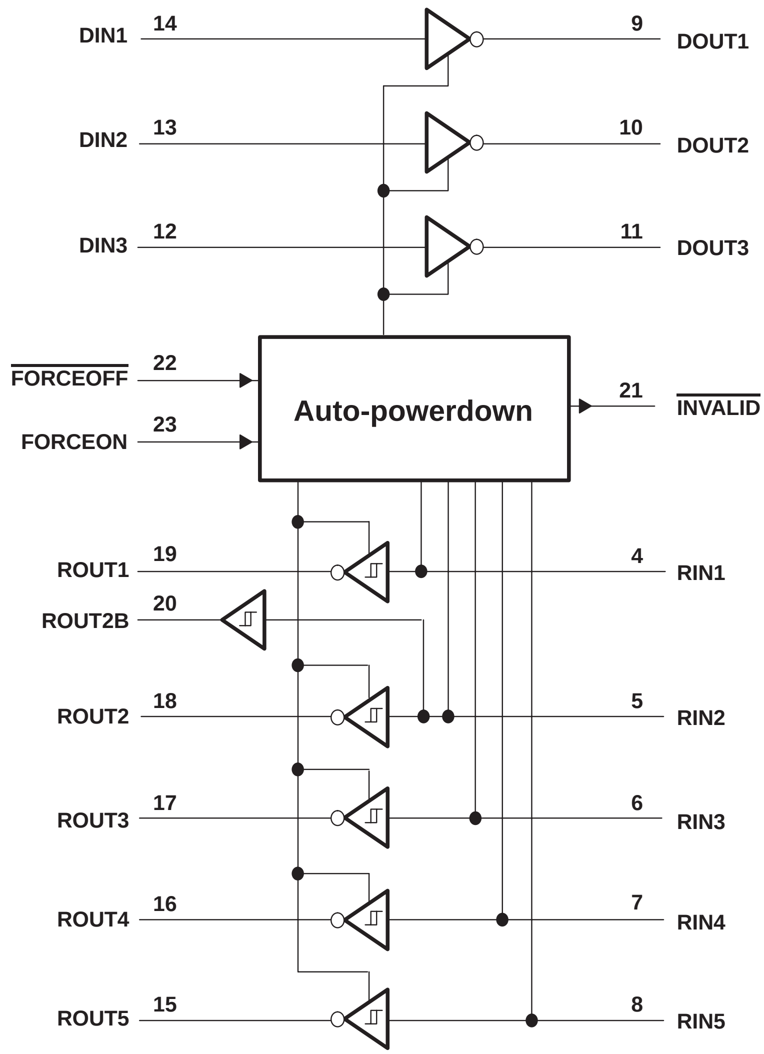
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

INPUTS				OUTPUTS		RECEIVER STATUS
RIN2	RIN1, RIN3−RIN5	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	
L	X	L	X	L	Z	Powered off while ROUT2B is active
H	X	L	X	H	Z	
L	L	H	Yes	L	H	Normal operation with auto-powerdown disabled/enabled
L	H	H	Yes	L	L	
H	L	H	Yes	H	H	
H	H	H	Yes	H	L	
Open	Open	H	No	L	H	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1) . . . . −0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1) . . . . −0.3 V to 7 V
Negative output supply voltage range, V− (see Note 1) . . . . 0.3 V to −7 V
Supply voltage difference, V+ − V− (see Note 1) . . . . 13 V
Input voltage range, V_I: Driver ($\overline{\text{FORCEOFF}}$, FORCEON) . . . . −0.3 V to 6 V
Receiver . . . . −25 V to 25 V
Output voltage range, V_O: Driver . . . . −13.2 V to 13.2 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package . . . . 62°C/W
DW package . . . . 46°C/W
PW package . . . . 62°C/W
Operating virtual junction temperature, T_J . . . . 150°C
Storage temperature range, T_{stg} . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.
2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V_{CC} = 3.3 V	3	3.3	3.6	V
			V_{CC} = 5 V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 3.3 V	2			V
			V_{CC} = 5 V	2.4			
V_{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON				0.8	V
V_I	Driver and control input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON		0		5.5	V
V_I	Receiver input voltage			−25		25	V
T_A	Operating free-air temperature		SN65C3243	−40		85	°C
			SN75C3243	0		70	

NOTE 4: Test conditions are C1−C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2−C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER			TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
I_I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON			±0.01	±1	µA
I_{CC}	Supply current	Auto-powerdown disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON = V_{CC}		0.3	1	mA
		Powered off	No load, $\overline{\text{FORCEOFF}}$ = GND		1	10	µA
		Auto-powerdown enabled	No load, $\overline{\text{FORCEOFF}}$ = V_{CC}, FORCEON = GND, All RIN are open or grounded, All DIN are grounded		1	10	

‡ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4. Test conditions are C1−C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2−C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	All DOUT at R_L = 3 kΩ to GND			5	5.4		V
V_{OL}	Low-level output voltage	All DOUT at R_L = 3 kΩ to GND			−5	−5.4		V
V_O	Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DIN3 = V_{CC}, 3-kΩ to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA			±5			V
I_{IH}	High-level input current	$V_I = V_{CC}$				±0.01	±1	μA
I_{IL}	Low-level input current	V_I = GND				±0.01	±1	μA
I_{OS}	Short-circuit output current‡	V_{CC} = 3.6 V,	V_O = 0 V			±35	±60	mA
		V_{CC} = 5.5 V,	V_O = 0 V			±35	±75	
r_o	Output resistance	V_{CC}, V+, and V− = 0 V,	V_O = ±2 V		300	10M		Ω
I_{off}	Output leakage current	$\overline{\text{FORCEOFF}}$ = GND	V_O = ±12 V,	V_{CC} = 3 V to 3.6 V			±25	μA
			V_O = ±10 V,	V_{CC} = 4.5 V to 5.5 V			±25	

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
‡ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.
NOTE 4. Test conditions are C1−C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2−C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
	Maximum data rate (see Figure 1)	R_L = 3 kΩ, One DOUT switching	C_L = 1000 pF		250			kbit/s
			C_L = 250 pF,	V_{CC} = 3 V to 4.5 V	1000			
			C_L = 1000 pF,	V_{CC} = 4.5 V to 5.5 V	1000			
$t_{sk(p)}$	Pulse skew§	C_L = 150 pF to 2500 pF,	R_L = 3 kΩ to 7 kΩ,	See Figure 2		25		ns
SR(tr)	Slew rate, transition region (see Figure 1)	C_L = 150 pF to 1000 pF,	R_L = 3 kΩ to 7 kΩ,	V_{CC} = 3.3 V	24		150	V/μs

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
§ Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.
NOTE 4. Test conditions are C1−C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2−C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = −1 mA	V_{CC} − 0.6 V	V_{CC} − 0.1 V		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6 mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 3.3 V		1.6	2.4	V
		V_{CC} = 5 V		1.9	2.4	
V_{IT-}	Negative-going input threshold voltage	V_{CC} = 3.3 V	0.6	1.1		V
		V_{CC} = 5 V	0.8	1.4		
V_{hys}	Input hysteresis (V_{IT+} − V_{IT-})			0.5		V
I_{off}	Output leakage current (except ROUT2B)	$\overline{\text{FORCEOFF}}$ = 0 V		±0.05	±10	µA
r_i	Input resistance	V_I = ±3 V to ±25 V	3	5	7	kΩ

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
NOTE 4. Test conditions are C1−C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2−C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER		TEST CONDITIONS	TYP†	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 150 pF, See Figure 3	150	ns
t_{PHL}	Propagation delay time, high- to low-level output	C_L = 150 pF, See Figure 3	150	ns
t_{en}	Output enable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
t_{dis}	Output disable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
$t_{sk(p)}$	Pulse skew‡	See Figure 3	50	ns

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
‡ Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.
NOTE 4. Test conditions are C1−C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2−C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

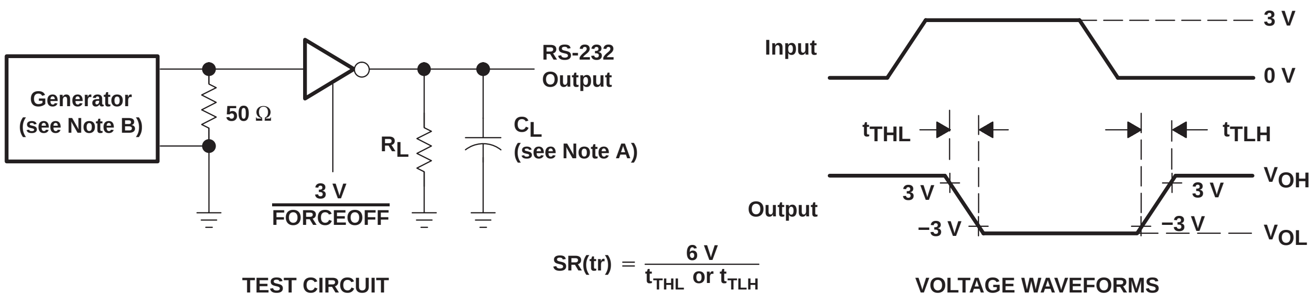
PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{\text{INVALID}}$ high-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}		2.7	V
$V_{T-(valid)}$	Receiver input threshold for $\overline{\text{INVALID}}$ high-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	−2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{\text{INVALID}}$ low-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	−0.3	0.3	V
V_{OH}	$\overline{\text{INVALID}}$ high-level output voltage	I_{OH} = −1 mA, FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	V_{CC} − 0.6		V
V_{OL}	$\overline{\text{INVALID}}$ low-level output voltage	I_{OL} = 1.6 mA, FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}		0.4	V

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TYP†	UNIT
t_{valid}	Propagation delay time, low- to high-level output	1	µs
$t_{invalid}$	Propagation delay time, high- to low-level output	30	µs
t_{en}	Supply enable time	100	µs

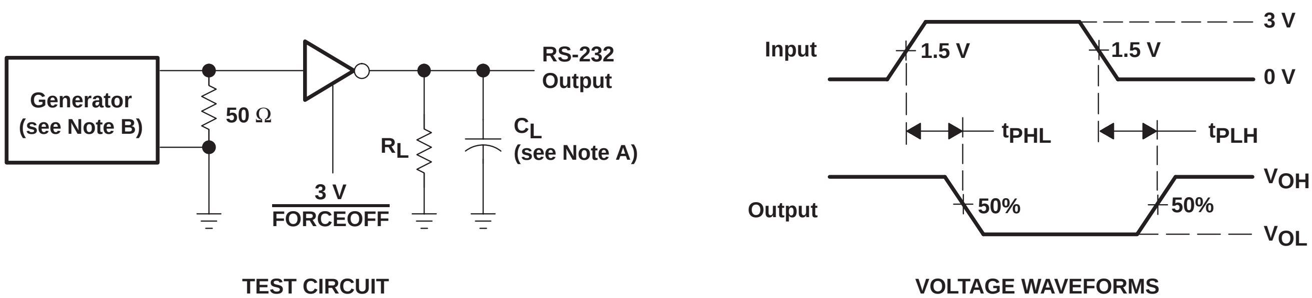
† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



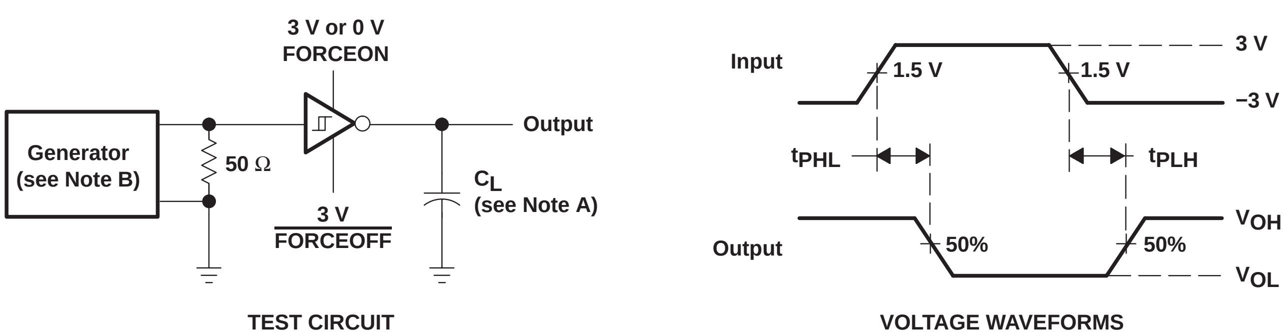
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns.

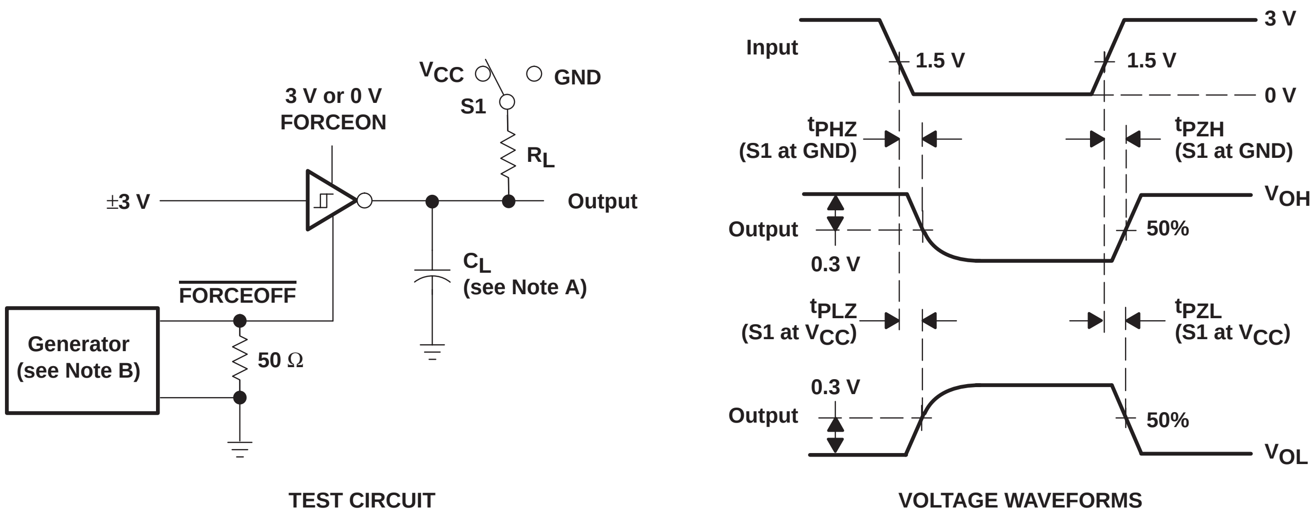
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns.

Figure 3. Receiver Propagation Delay Times

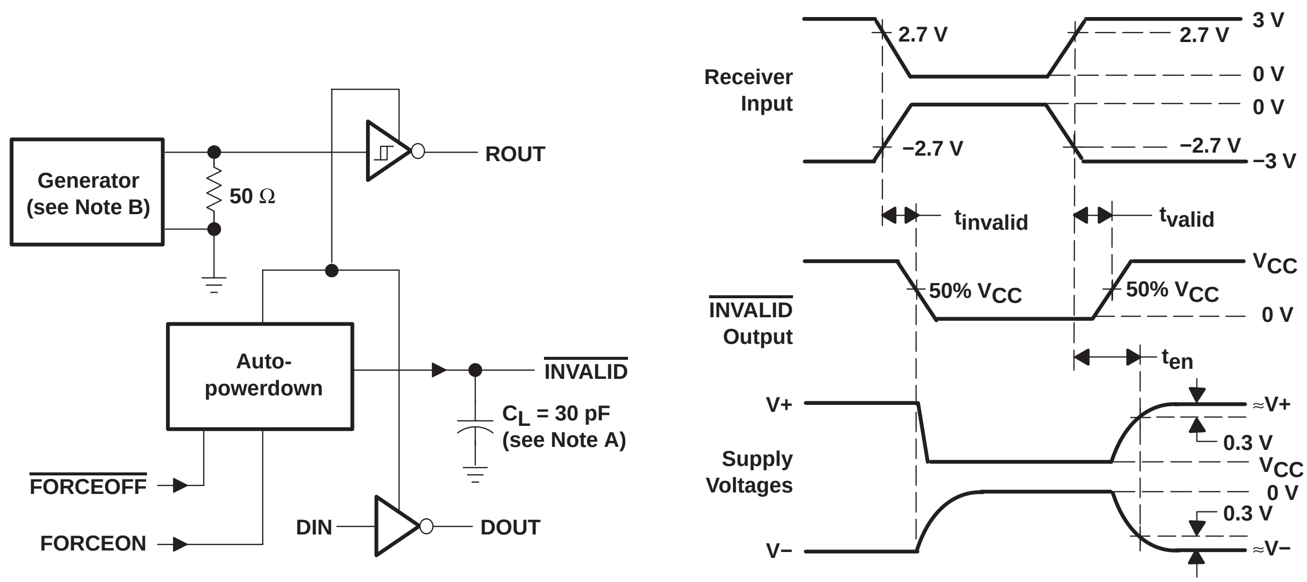
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns.
C. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
D. t_{PZL} and t_{PZH} are the same as t_{en}.

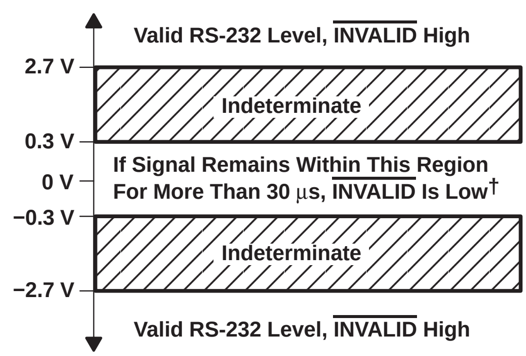
Figure 4. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

VOLTAGE WAVEFORMS

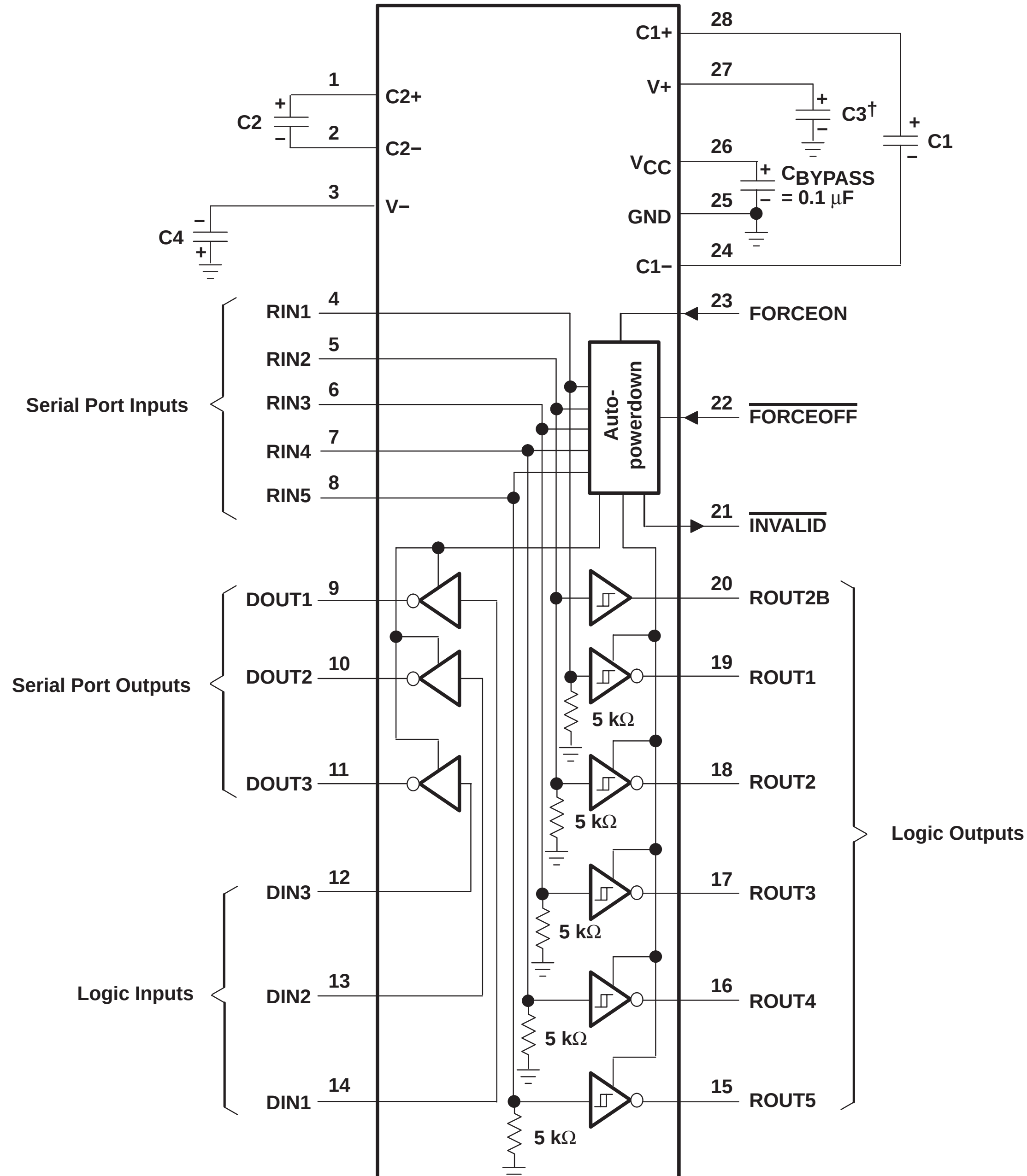


† Auto-powerdown disables drivers and reduces supply current to 1 µA.

NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.
NOTE A: Resistor values shown are nominal.

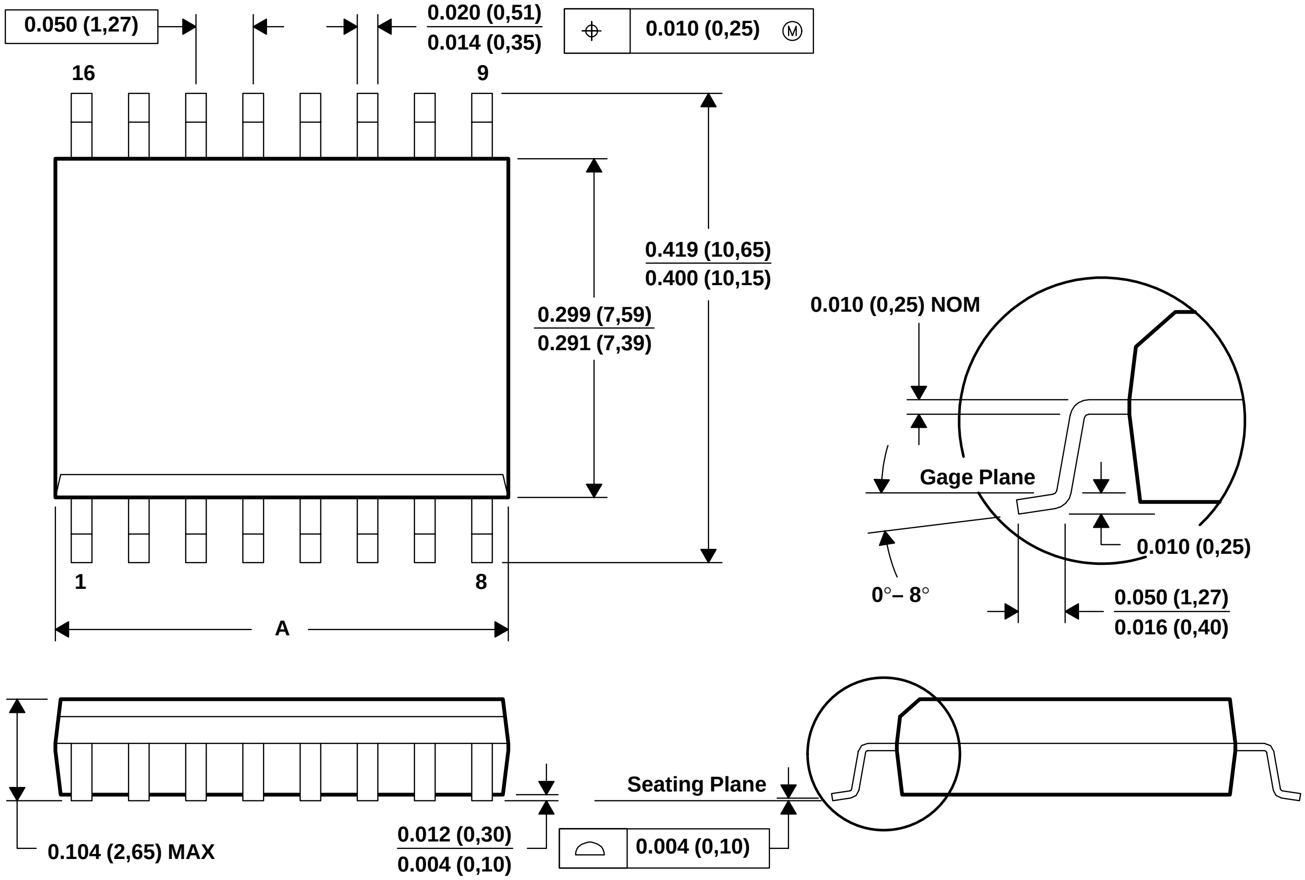
V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V ± 0.3 V	0.1 µF	0.1 µF
5 V ± 0.5 V	0.047 µF	0.33 µF
3 V to 5.5 V	0.1 µF	0.47 µF

Figure 6. Typical Operating Circuit and Capacitor Values

DW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

16 PINS SHOWN



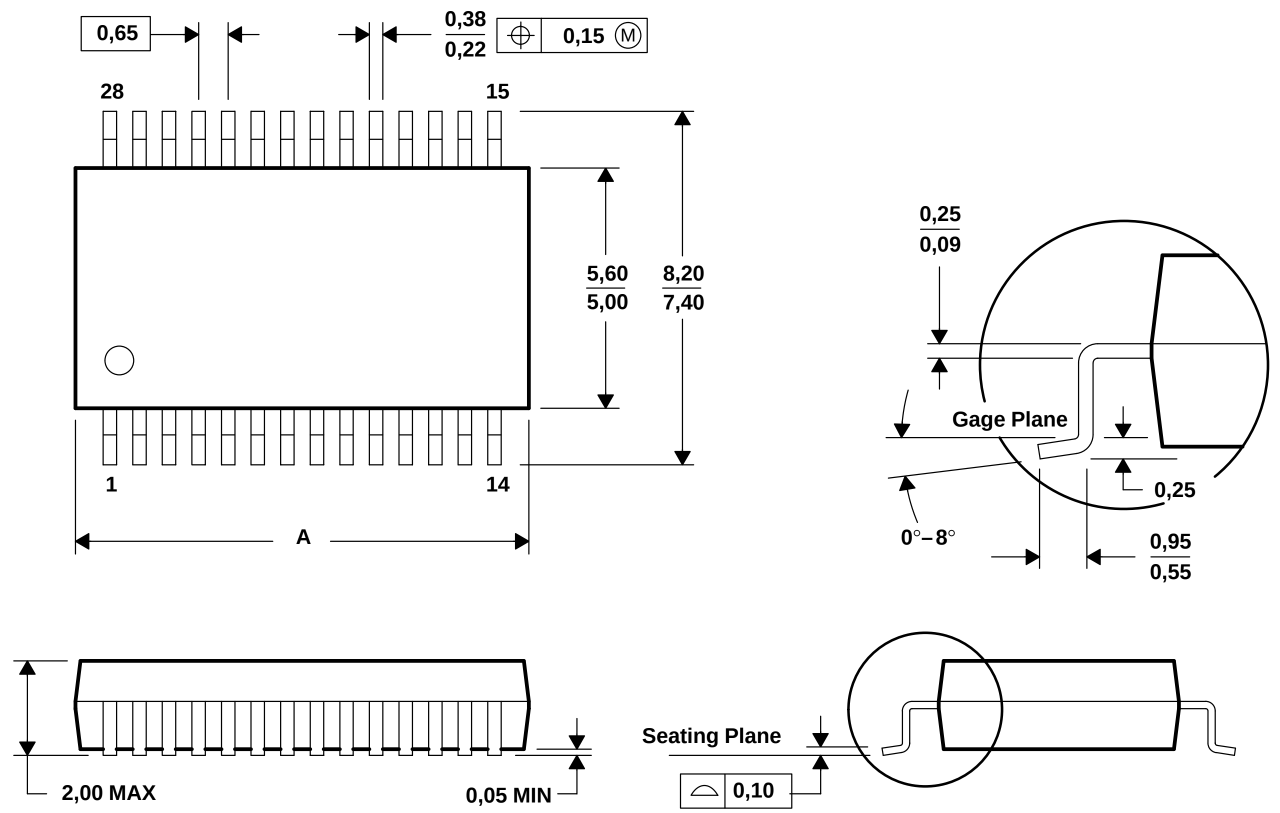
DIM \ PINS **	16	18	20	24	28
A MAX	0.410 (10,41)	0.462 (11,73)	0.510 (12,95)	0.610 (15,49)	0.710 (18,03)
A MIN	0.400 (10,16)	0.453 (11,51)	0.500 (12,70)	0.600 (15,24)	0.700 (17,78)

4040000/E 08/01

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



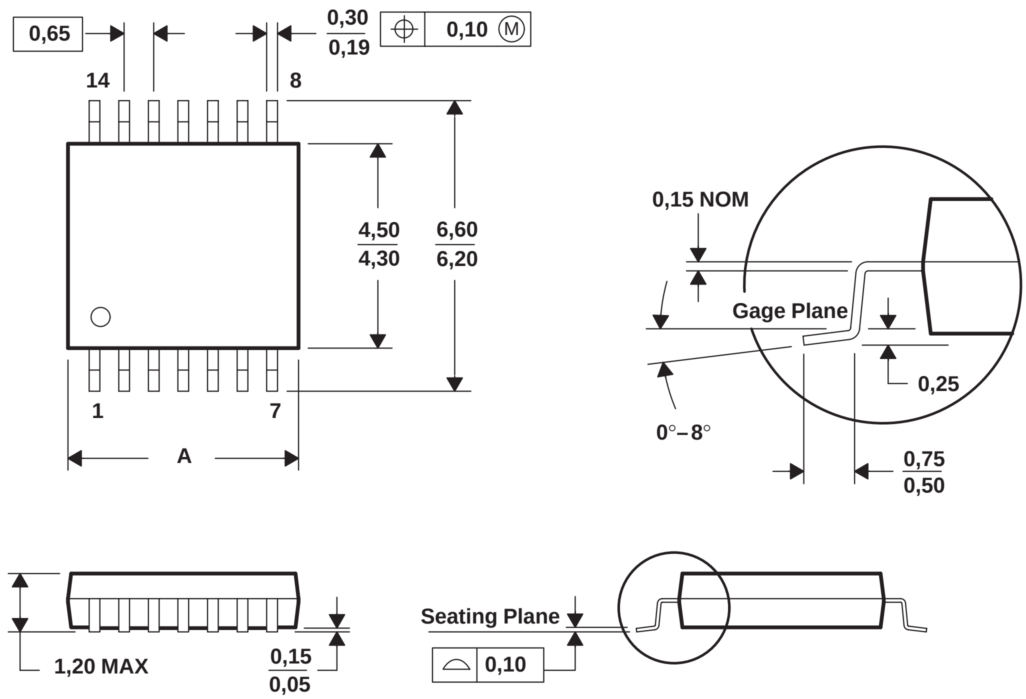
PINS ** / DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



PINS ** / DIM	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265